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P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)			
- 60	$0.045 \text{ at V}_{GS} = -10 \text{ V}$	- 40 ^d			
- 60	0.054 at V _{GS} = - 4.5 V	- 40 ^d			

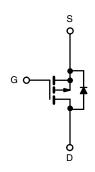
FEATURES

- DT-Trench Power MOSFET
- Material categorization:

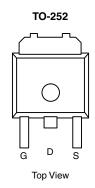


APPLICATIONS

Load Switch



P-Channel MOSFET



Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 60	V		
Gate-Source Voltage	V _{GS}	± 20	7 v		
Continuous Drain Current (T _{.I} = 175 °C)	T _C = 25 °C	I _D	- 40 ^d		
Continuous Diam Current (1) = 173 C)	T _C = 125 °C	'D	- 27.5	٦ ,	
Pulsed Drain Current	I _{DM}	- 110	A		
Avalanche Current	I _{AS}	- 30	1		
Single Pulse Avalanche Energy ^a	L = 0.1 mH	E _{AS}	125	mJ	
Dower Dissipation	T _C = 25 °C	P _D	113 ^c	w	
Power Dissipation	T _A = 25 °C	LD _	2.5 ^{b, c}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Junction-to-Ambient ^b	t ≤ 10 s	R _{thJA}	15	18	°C/W	
Junction-to-Ambient	Steady State		40	50		
Junction-to-Case		R_{thJC}	0.82	1.1		

Notes:

- a. Duty cycle \leq 1 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. See SOA curve for voltage derating.
- d. Package limited.



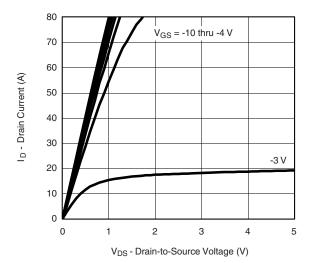
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 60 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ	
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 150 °C			- 100		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 50			Α	
		V _{GS} = - 10 V, I _D = - 5 A	0.045		0.055		
D : 0	D	V _{GS} = - 10 V, I _D = - 10 A, T _J = 125 °C			0.065	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 10 A, T _J = 150 °C			0.073		
		V _{GS} = - 4.5 V, I _D = - 5 A		0.054	0.069		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 17 A		61		S	
Dynamic ^b				-	•		
Input Capacitance	C _{iss}			4950			
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		480		pF	
Reverse Transfer Capacitance	C _{rss}			405			
Total Gate Charge ^c	Q_g			110	165		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -40 \text{ A}$		19		nC	
Gate-Drain Charge ^c	Q_{gd}]		28			
Turn-On Delay Time ^c	t _{d(on)}			15	23		
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 0.6 Ω		70	105	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -40 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 6$		175	260		
Fall Time ^c	t _f	Ω		175	260		
Source-Drain Diode Ratings and Cha	racteristics -	T _C = 25 °C ^b		•			
Continuous Current	IS				- 40	٨	
Pulsed Current	I _{SM}				- 80	Α	
Forward Voltage ^a	V _{SD}	I _F = - 40 A, V _{GS} = 0 V		- 1	- 1.6	V	
Reverse Recovery Time	t _{rr}	I _F = - 40 A, dI/dt = 100 A/μs		45	70	ns	

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

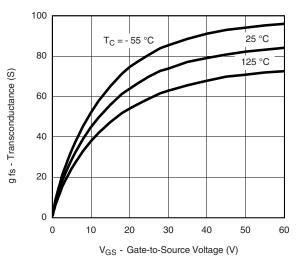
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



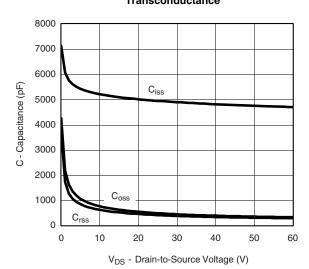
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



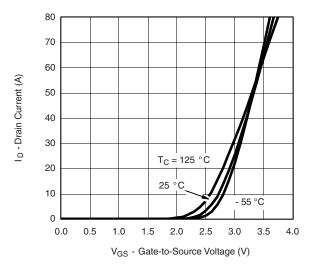
Output Characteristics



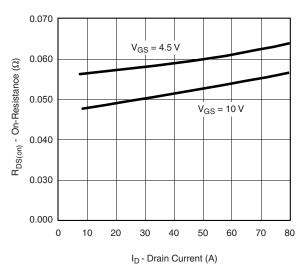
Transconductance



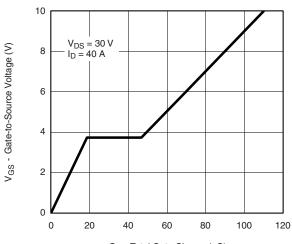
Capacitance



Transfer Characteristics



On-Resistance vs. Drain Current

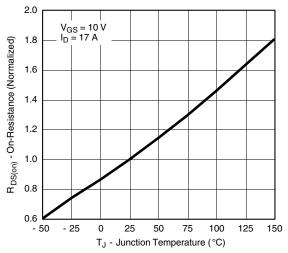


 $\mathbf{Q}_{\mathbf{g}}$ - Total Gate Charge (nC)

Gate Charge

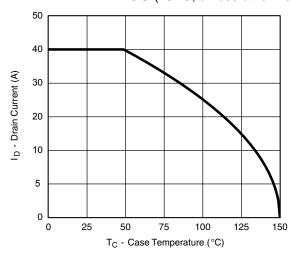


TYPICAL CHARACTERISTICS

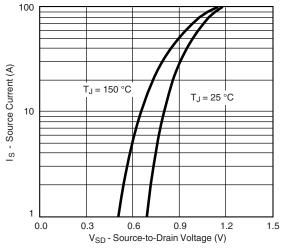


On-Resistance vs. Junction Temperature

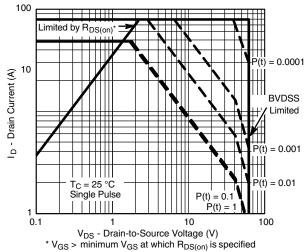
THERMAL RATINGS (25 °C, unless otherwise noted)



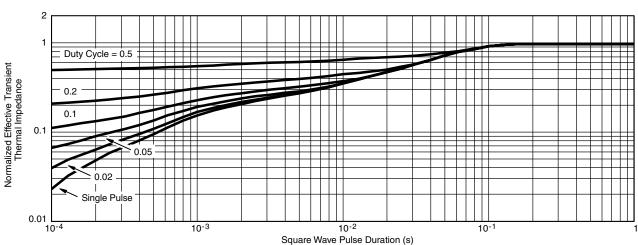
Drain Current vs. Case Temperature



Source-Drain Diode Forward Voltage



Safe Operating Area

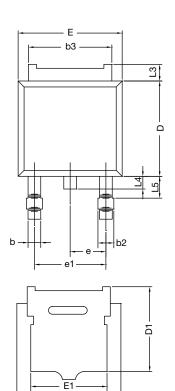


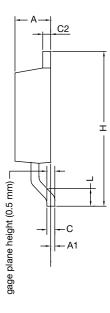
Normalized Thermal Transient Impedance, Junction-to-Case





TO-252AA CASE OUTLINE





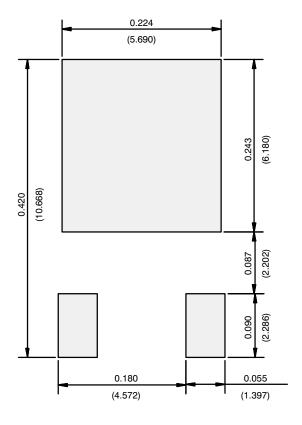
	MILLIN	METERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	BSC			
e1	4.56 BSC		0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12						

DWG: 5347 Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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